TOREX SEMICONDUCTOR LTD.
Quality Assurance Dept.

Composition Table

Product(Pb-free):	XC61CxxxxxNR-G	
Typical Mass:	7	mg

Part name	Weight(mg)	Material name	Ratio(ppm)	CAS number
Silicon chip	0.246	Silicon	35200	7440-21-3
Leadframe	2.790	Copper	398500	7440-50-8
	0.066	Tin	9400	7440-31-5
	0.001	Zinc	100	7440-66-6
	0.003	Chromium	400	7440-47-3
	0.071	Silver	10100	7440-22-4
Die attach	0.013	Silver	1900	7440-22-4
	0.001	Epoxy	200	—
Bonding wire	0.030	Gold	4300	7440-57-5
Resin	3.150	Silica	450000	60676-86-0
	0.251	Epoxy Resin	35800	—
	0.179	Phenol Resin	25600	—
Plating	0.200	Tin	28600	7440-31-5

* The component composition is based on the information provided by raw material vender.

* The mass of the IC and its fractions could be different due to the manufacturing conditions of materials.

* Any indication "-" in CAS number means "confidential."